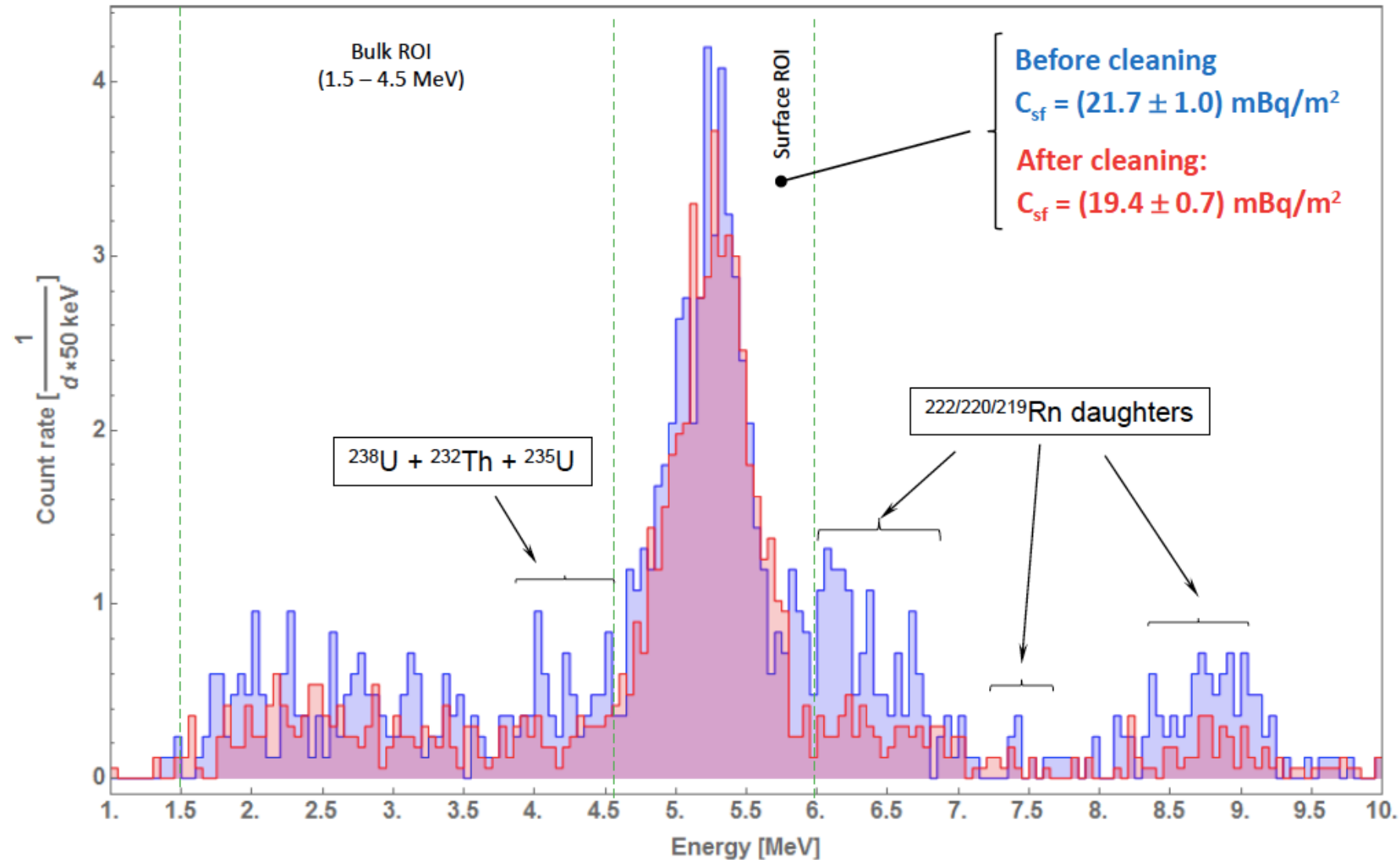


Surface Treatments Updates Copper Cleaning Protocol

DS Copper Cleaning Protocol:

1. 4 Copper plates (100x100mm) are measured showing ^{210}Po residual contaminants



DS cleaning Protocol vs CUORE cleaning Protocol

DS

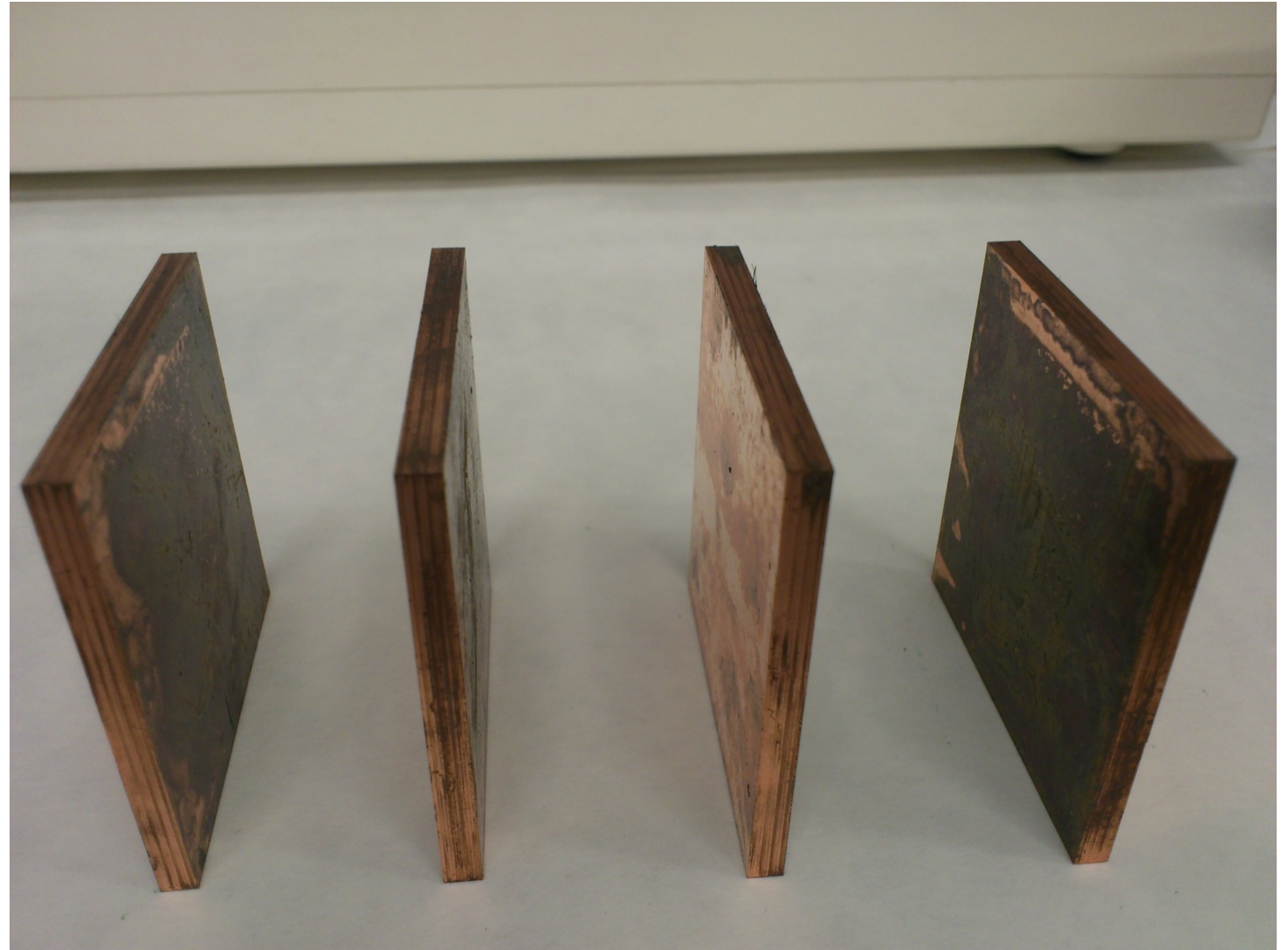
1. Tumbling
2. EP 100 μm
3. SUBU (Etching)

CUORE

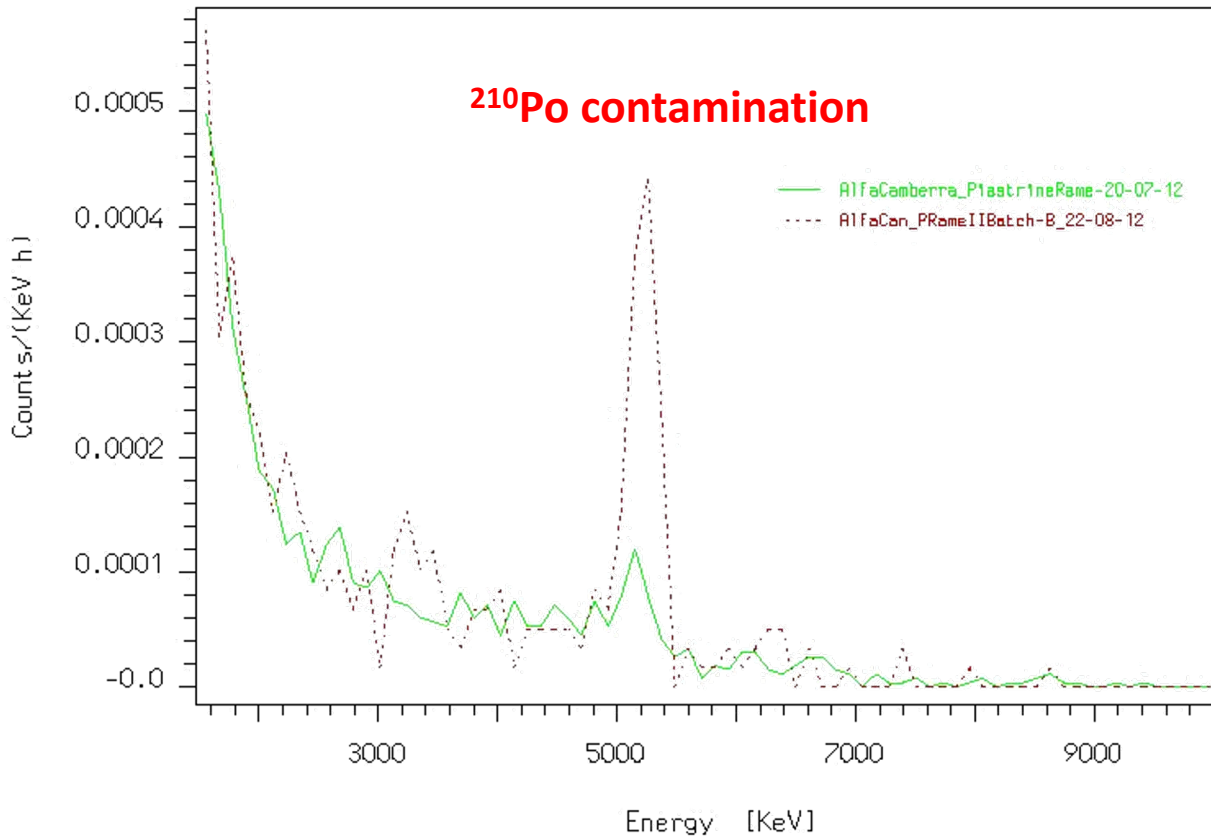
1. Tumbling
2. EP 100 μm
3. SUBU (Etching)
4. Vacuum Plasma Cleaning

Copper Test Samples (CUORE Quality Check)

Before each new cleaning batch we tested 50X50 mm squared copper samples

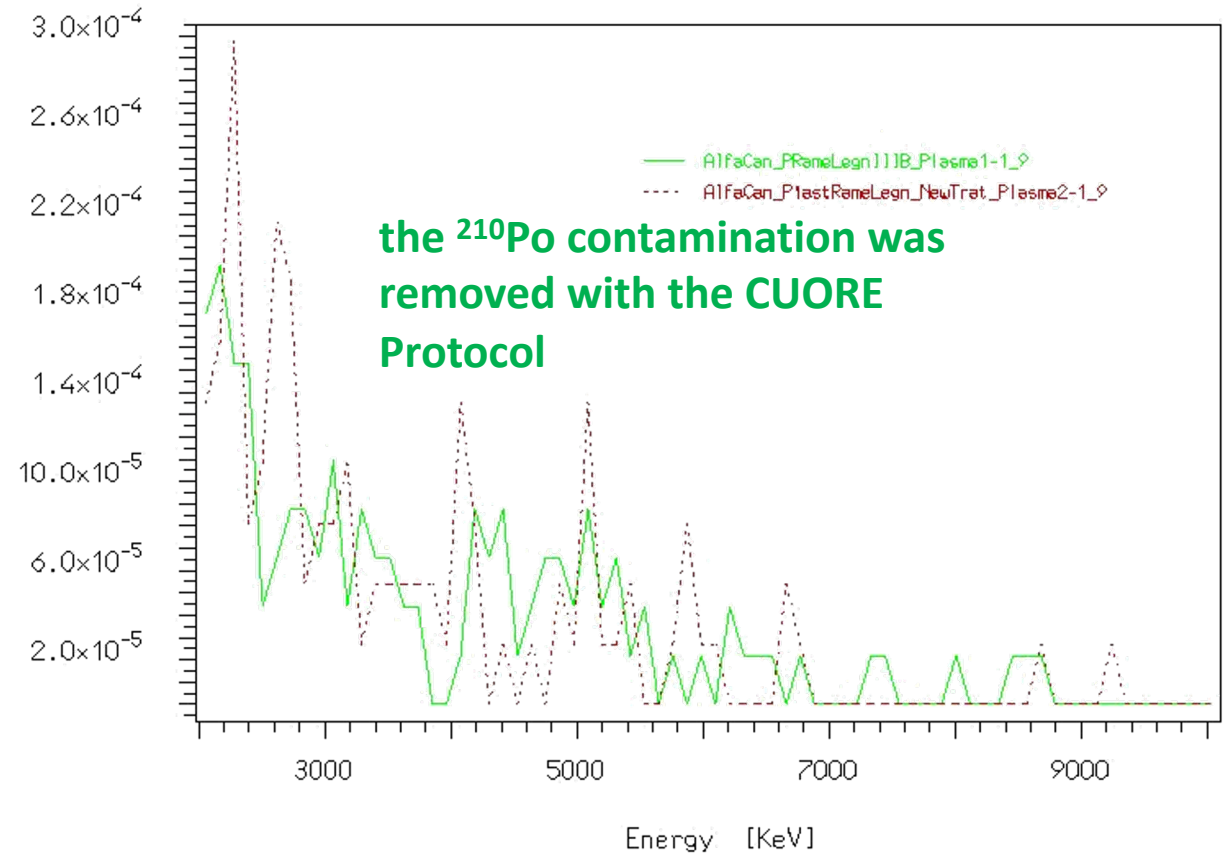


Plasma1 Vs Plasma2 ^{210}Po contamination (Before the production with Plasma 2)



Thu Aug 23 09:55:14 2012

Plasma1 Vs Plasma2 ^{210}Po contamination (after the CUORE cleaning protocol)



Fri Oct 12 14:10:48 2012

Considerations on the Copper Cleaning Protocol

Up to now the DS protocol under investigation doesn't remove ^{210}Po .

Possible solutions:

1. Multiple short etching as reported in Grzegorz study
2. The complete CUORE Protocol adding the Vacuum Plasma Cleaning

In both cases it will modify the production schedule of the DS Motherboards.

We are starting the MB cleaning, we received 20 MB to clean, before the end of the year.

There is no more time to decide (probably a meeting is needed to take the final decision).

Surface Treatments Updates Stainless Steel Cleaning Protocol

DS SS Cleaning Protocol:

1. 4 Copper plates (100x100mm) are at LNL ready to be cleaned
2. We have first to define the right SS composition (304, 316...?) to adopt the right EP and etching solution
3. New setup dedicated to SS in order to avoid contamination of the copper plant
4. We could have the option to test the EP in outsource (Company for the EP of VETO SS): to verify with Alessio Caminata.

Surface Treatments Updates Conformal Coating for Electronic shielding

DS Conformal Coating:

1. Waiting for the results at LNGS for the Sprayed or Dipped conformal coating (Alessandro Razeto)
2. Following this result we will go ahead or not with Parylene R&D